

WHAT IS CLAIMED IS:

1 1. A semiconductor device comprising:
2 545 B1> a. a leadframe including a plurality of leads extending therefrom, a first
3 source attach area on a first surface of the leadframe and a first gate attach area, and a second
4 source attach area on a second surface of the leadframe and a second gate attach area;
5 b. at least two dies, a first of which is coupled to the first source and gate
6 attach areas and a second of which is coupled to the second source and gate attach areas;
7 c. a drain connection assembly coupled to a drain region of the first die;
8 and,
9 a body, the body being coupled to the semiconductor device such that a drain
10 region of the second die is exposed.

1 2. A semiconductor device in accordance with claim 1 wherein at least
2 one of the dies is a bumped die.

1 3. A semiconductor device in accordance with claim 2 wherein both dies
2 are bumped dies.

1 4. A semiconductor device in accordance with claim 1 wherein the drain
2 connection assembly comprises a drain clip and a lead rail adjacent an edge of the drain clip.

1 5. A method of of making a semiconductor device, the method
2 comprising:
3 providing a leadframe including a plurality of leads extending therefrom, a
4 first source attach area on a first surface of the leadframe and a first gate attach area, and a
5 second source attach area on a second surface of the leadframe and a second gate attach area;
6 bonding a first die to the first source and gate attach areas with solder;
7 reflowing the solder;
8 bonding a second die to the second source and gate attach areas with second
9 solder;
10 bonding a drain connection assembly to a drain region of the second die with
11 third solder;
12 reflowing at least the third solder; and
13 coupling a body to the semiconductor device such that a drain region of the
14 second die is exposed.

- 1 6. A method in accordance with claim 5 further comprising reflowing the
2 second solder prior to bonding the drain connection assembly to the drain region of the
3 second die.
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